

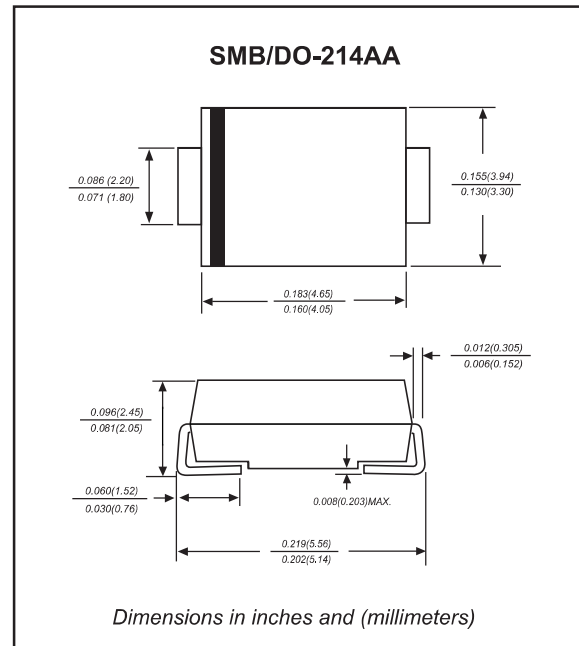
Features

- ◆ The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- ◆ For surface mounted applications
- ◆ Metal silicon junction, majority carrier conduction
- ◆ Low power loss, high efficiency
- ◆ Built-in strain relief, ideal for automated placement
- ◆ High forward surge current capability
- ◆ High temperature soldering guaranteed: 260°C/10 seconds at terminals
- ◆ Compliant to RoHS 2.0

Mechanical data

- ◆ **Case:** JEDEC DO-214AA molded plastic body
- ◆ **Terminals:** Solder plated, solderable per MIL-STD-750, Method 2026
- ◆ **Polarity:** Color band denotes cathode end
- ◆ **Mounting Position:** Any

Package outline



MAXIMUM RATINGS

| Rating | Symbol | Value | Unit |
|---|---------------------------------|-------------|------------------|
| Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage | V_{RRM} V_{RWM} V_R | 200 | V |
| Average Rectified Forward Current ($T_L = 150^\circ\text{C}$) | $I_{F(AV)}$ | 3.0 | A |
| Non-Repetitive Peak Surge Current (Surge Applied at Rated Load Conditions Halfwave, Single Phase, 60 Hz) | I_{FSM} | 100 | A |
| Operating Junction Temperature | T_J | -65 to +175 | $^\circ\text{C}$ |

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL CHARACTERISTICS

| Characteristic | Symbol | Value | Unit |
|--|-----------------|-------|--------------------|
| Thermal Resistance, Junction-to-Lead (Note 1) | $R_{\theta JL}$ | 13 | $^\circ\text{C/W}$ |
| Thermal Resistance, Junction-to-Ambient (Note 2) | $R_{\theta JA}$ | 62 | $^\circ\text{C/W}$ |

ELECTRICAL CHARACTERISTICS

| | | | |
|--|-------|----------------------|----------|
| Maximum Instantaneous Forward Voltage (Note 3) ($I_F = 3.0\text{ A}$, $T_J = 25^\circ\text{C}$) ($I_F = 4.0\text{ A}$, $T_J = 25^\circ\text{C}$) ($I_F = 3.0\text{ A}$, $T_J = 150^\circ\text{C}$) | V_F | 0.84 0.86 0.59 | V |
| Maximum Instantaneous Reverse Current (Note 3) (Rated dc Voltage, $T_J = 25^\circ\text{C}$) (Rated dc Voltage, $T_J = 150^\circ\text{C}$) | I_R | 1.0 5.0 | mA mA |

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

1. Minimum pad size (0.108 × 0.085 inch) for each lead on FR4 board.
2. 1 inch square pad size (1 × 0.5 inch) for each lead on FR4 board.
3. Pulse Test: Pulse Width = 300 μs , Duty Cycle $\leq 2.0\%$.

Rating and characteristic curves

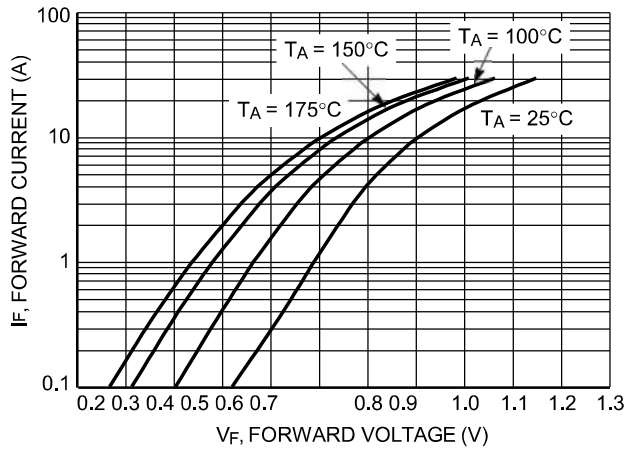


Figure 1. Typical Forward Voltage

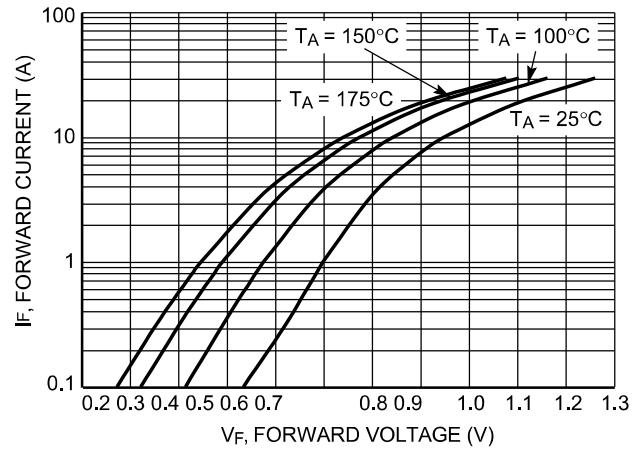


Figure 2. Maximum Forward Voltage

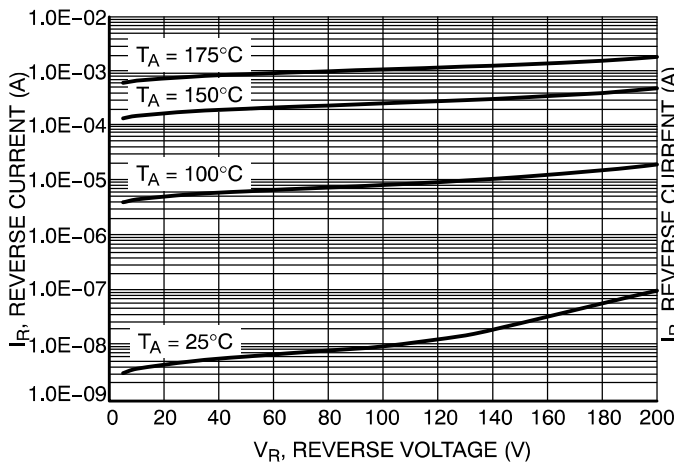


Figure 3. Typical Reverse Current

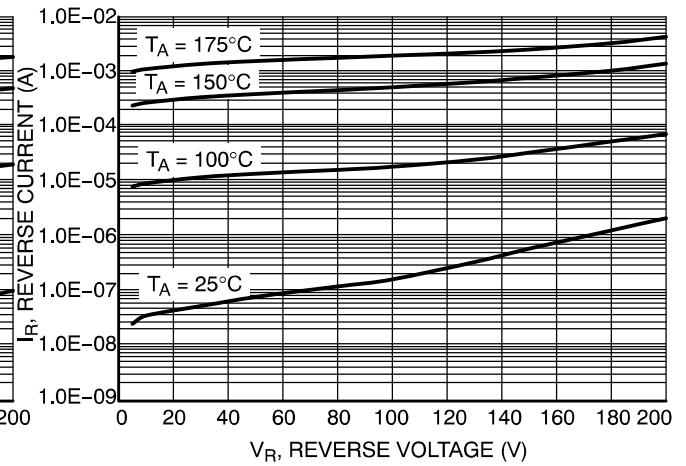


Figure 4. Maximum Reverse Current

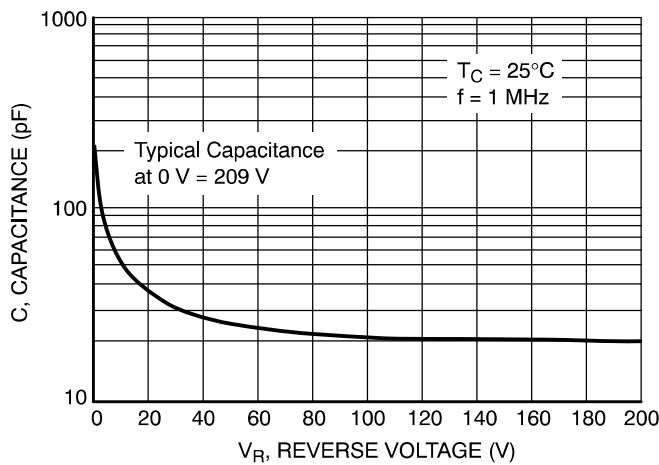


Figure 5. Typical Capacitance

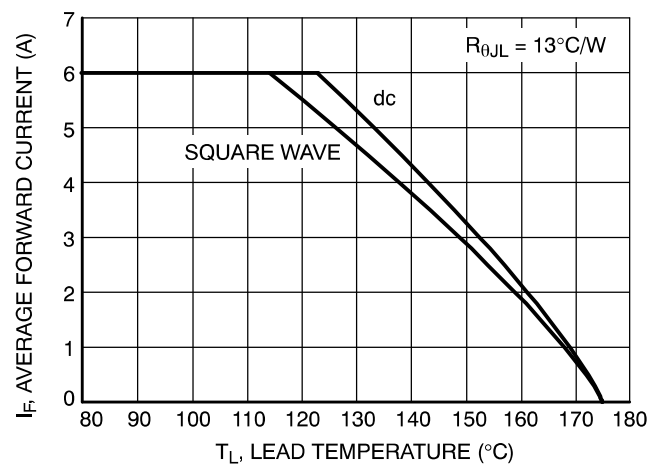


Figure 6. Current Derating - Lead

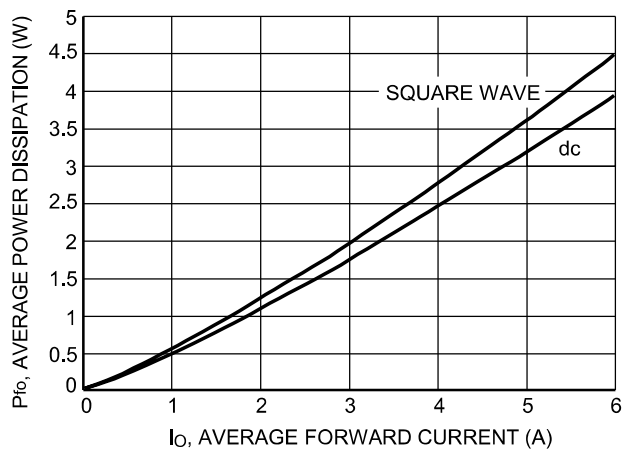


Figure 7. Forward Power Dissipation

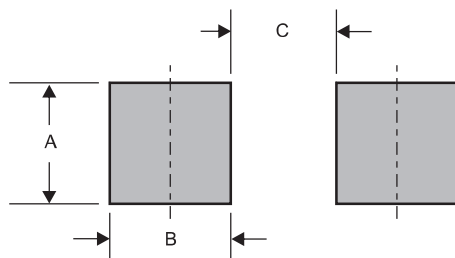
Pinning information

| Pin | Simplified outline | Symbol |
|----------------------------|--------------------|--------|
| Pin1 cathode Pin2 anode | | |

Marking

| Type number | Marking code | Example |
|-------------|--------------|---------|
| MBRS3200T3G | B320 | |

Suggested solder pad layout



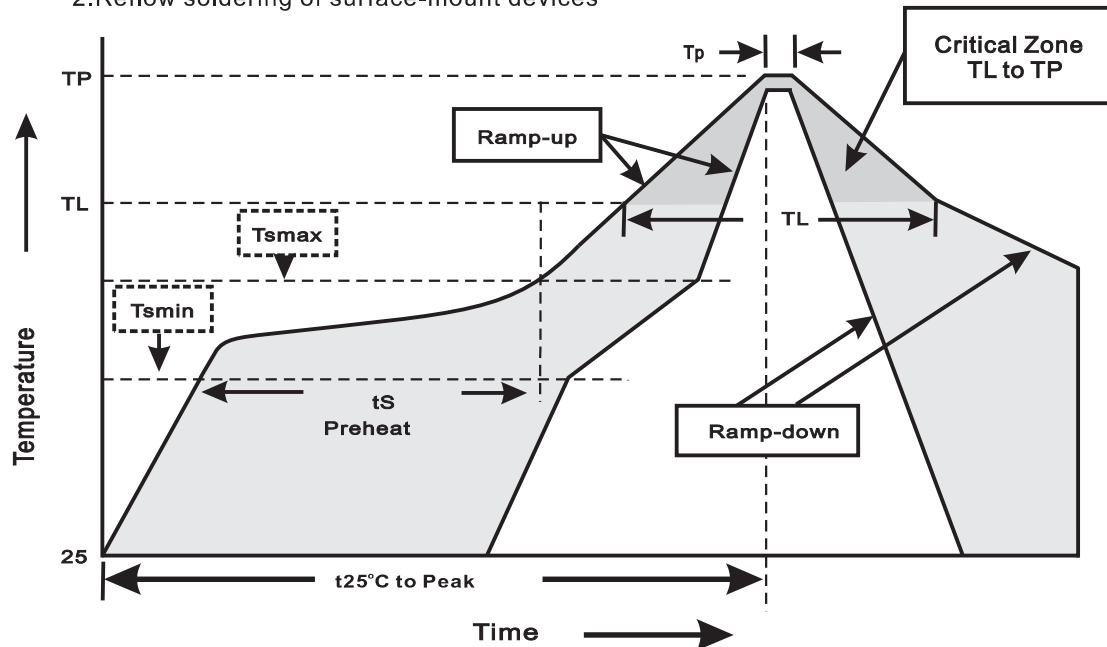
Dimensions in inches and (millimeters)

| PACKAGE | A | B | C |
|---------|--------------|--------------|--------------|
| SMB | 0.078 (2.00) | 0.059 (1.50) | 0.110 (2.80) |

Suggested thermal profiles for soldering processes

1.Storage environment: Temperature=5°C~40°C Humidity=55%±25%

2.Reflow soldering of surface-mount devices



3.Reflow soldering

| Profile Feature | Soldering Condition |
|---|-----------------------------|
| Average ramp-up rate(T _L to T _P) | <3°C/sec |
| Preheat -Temperature Min(T _{smmin}) -Temperature Max(T _{smmax}) -Time(min to max)(t _s) | 150°C 200°C 60~120sec |
| T _{smmax} to T _L -Ramp-upRate | <3°C/sec |
| Time maintained above: -Temperature(T _L) -Time(t _L) | 217°C 60~260sec |
| Peak Temperature(T _P) | 255°C-0/+5°C |
| Time within 5°C of actual Peak Temperature(t _P) | 10~30sec |
| Ramp-down Rate | <6°C/sec |
| Time 25°C to Peak Temperature | <6minutes |